TECHNICAL DATA SHEET

QLE 1051
1 Part Non-Corrosive Neutral Cure Adhesive Sealant and Potting Material (Electronic Grade)

Description

This is a one-component, self-bonding elastomer designed for use in semiconductor applications. The material has excellent adhesion to many substrates.

Key Features

- 100% solids
- Two hour cure time at 150°C/302°F
- Fast cure at elevated temperatures
- Primerless adhesion to a variety of substrates

Application

Semiconductor applications

Use and Cure Information

This material is a one-component, white, heat-cured silicone elastomer. The material should only be used on clean surfaces to maximize adhesion properties. In addition, some substrates may be difficult to bond to and some, such as galvanized metal, may cause cure inhibition. When this occurs, a primer can be used to eliminate this problem.

Revision Date	07 May 2024
Revision No	4
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Property	Test Method	Value
Uncured Product		
Cure Type		**Addition**
Rheology		**Liquid**
Self Bonding		**Yes**
Specific Gravity		**1.50**
Viscosity	Brookfield	**14,500 cP**
Cured Product		
60 minutes at 150°C		
Color		**White**
Elongation at Break	ISO 37	**100 %**
Hardness Shore A	ASTM D 2240-95	**75**
Max Working Temp		**204 °C / 399 °F**
Min Working Temp		**-55 °C / -67 °F**
Tensile Strength	ISO 37	**6.21 N/mm2 / 900 psi**
Electrical Properties		
Dielectric Constant	ASTM D-150	**2.8**
Dissipation Factor	ASTM D-150	**0.017**
Volume Resistivity (Ohms cm)	ASTM D-257	**7E+14 ohms cm**
Storage		
Max Storage Temperature		**4.4 °C / 40 °F**
Shelf Life		**12 mths**

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